



X-ray Photoelectron Spectroscopy (XPS) Auger Electron Spectroscopy (AES)

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X-ray Photoelectron Spectroscopy







 $B.E. = h\nu - K.E. - \phi$

-surface elements -chemical states

Semiconductor energy levels

2s



X-ray Photoelectron Spectroscopy

- Elemental and chemical state analysis of the outer surface of a solid samples
- Effective probing depth 5-10 nm
 - Varies slightly with sample composition
 - Can be varied with electron take-off (or sample) angle
- Detects elements from lithium to uranium
 - Quantitative
 - 0.01 to 0.5 atomic % detection limits
- Examples of chemical information that can be obtained
 - Metal oxides, hydroxides, carbides
 - Silicone, silica, silicon nitride or elemental silicon,
 - Fluorocarbon or fluoride,
 - Chromium 0, III or VI





Kratos AXIS Supra Spectrometer





Kratos AXIS Supra Spectrometer

- Large area 300x700 μm, 110, 55, 27 μm selected area spots
- Variable angle sample orientation (angle resolved analysis)
- High precision automated stage for remote or non-attended operation
- Depth profiling with both monoatomic Ar⁺ and gas cluster beams (up to Ar3000⁺)
- Interfaced to a glove box for chemical preparation under inert atmosphere
- Analysis of sample sizes up to 30 mm x 75 mm and up to 10 mm thick (can do larger samples on Nova instrument)
- Elemental and chemical imaging, small spot analysis
- Multiple X-ray sources including monochromatic Al Ka, monochromatic Ag La, He(I) and He(II)
- In-situ fracturing at low temperature
- Sample heating (800° C) and cooling (-100° C)
- Ion scattering spectroscopy (ISS) equipped



XPS Analysis of Crater Defects

- Crater defects on a car bumper (Zenoy substrate)
- Optical and SEM/EDX analysis revealed no significant differences between the crater area and a reference area of coating
- XPS, a much more surface sensitive technique, was used.







114.2

Inside the crater

110.2

106.2

Binding Energy

102.2

(eV)

98.2

94.2

• High resolution Si 2p spectra confirmed the presence of a single species of silicon in the crater - silicone

93.

97.7

Reference Area

109.7

113.7

105.7

Binding Energy

101.7

(eV)

improper mixing of additives may be responsible for the crater formation.

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XPS Analysis of Phosphated Steel

- A customer was finding large defective areas of e-coat on a zinc plated and phosphated steel.
- It had been noticed that white areas on the unpainted phosphated steel were of roughly the same size as that of the defects.
- Analysis of the white areas by XPS showed an increase in carbon compared to a normal area of phosphate coating
- The cause of the defects was then tracked to a organic compound on the surface of the phosphated steel.





- Usually, the binding energies of the oxide and the metallic species are separated by a few electron volts.
- Thus, when the oxide is thin (< 9 nm), it is possible to distinguish the contribution from both oxide and metal photoelectrons.
- For aluminum, oxide thickness (d) is given as:

d (nm) = 2.8 ln ((1.4(I_o/I_m))+1)

where I_o and I_m are the intensities (peak areas) of the oxide and metal photoelectron peaks respectively.



Estimation of Oxide Thickness



High resolution Al 2p spectrum of an aluminum surface. The aluminum metal and oxide peaks shown can be used to determine oxide thickness, in this case 3.7 nm



XPS Imaging – Paint Cross-Section





XPS Imaging – Paint Cross-Section



695 x 320 μm Elemental XPS Maps using C 1s, O 1s, Cl 2p and Si 2p signals



XPS Imaging – Paint Cross-Section



695 x 320 µm

C 1s Chemical State Maps



XPS Spot Mode From Images





XPS Summary

- Elemental and chemical state information from the outer 5-10 nm of a solid surface
- Most of solid samples can be analyzed
- Quantifiable
- All elements detectable except H and He with detection limits of 0.01 to 0.5 at. %
- Imaging and depth profiling of elements and/or chemical states



Auger Electron Spectroscopy





Auger Electron Spectroscopy



Also known as Scanning Auger Microscopy (SAM)



Auger Characteristics

- Depth probed: 0.5 5 nm (typically 0.5- 3 nm)
- All elements except H and He
- Non-destructive, except to electron beam sensitive materials and during depth profiling
- Elemental analysis, semi-quantitative without standard; quantitative with standards
- Absolute sensitivity: 0.1 at. % (1000 ppm) or lower for most elements, depending on the matrix
- Small spot analysis
- Line scans
- Depth profiling in combination with ion beam sputtering
- Imaging/mapping due to scanning system
- Vacuum (UHV) compatible samples

SURFACE SCIENCE PHI 710 Scanning Auger Nanoprobe



- 25 kV Schottky thermal field emission electron source
- ~ 4 nm SE dark space resolution (25 kV, 1 nA)
- ~ 8 nm Auger spatial resolution (20 kV, 1 nA)
- 8 channel coaxial cylindrical mirror analyzer (eliminates topography induced artifacts)
- High Energy Resolution Mode enables chemical state analysis
- Floating column argon ion gun surface cleaning, depth profiling, and charge neutralization
- In-situ parking and fracture stage



Oxidized Alloy 600 Coupon

- Alloy 600: (~ 70% Ni, 15% Cr and 10% Fe)
- Exposed to a high temperature and high-pressure autoclave for ~10 years.
- Contains crystals/deposits on surface ranging from a few µm to a few nm.







500 nm





Oxidized Alloy 600 Coupon

5000 X

20kV 10nA 128x128 pixels

2 µm





Copper Coated Steel



- Electrodeposited Cu on steel, with the upper cold spray Cu broken off (~ 0.2 mm Cu left on steel)
- Corroded 38 hours in oxygenated 3 M NaCl
- Iron(III) oxides (α-/β-/γ-FeOOH, γ-Fe₂O₃) are expected to be present inside the hole



Copper Coated Steel





Hastelloy G-35 Coupon

- 58% Ni, 33% Cr, 8.1% Mo, 2% Fe, W, Co and other trace elements
- Sample polished to 1 µm diamond paste and exposed for 6 hours in 1 M HCI + 2 M NaCl solution at 75 °C
- AES analysis conducted to investigate corrosion at the grain boundaries





Auger Depth Profiling



For each element, an Auger peak is selected for acquiring its intensity at each depth.

- Pt: MNN at 1697 eV
- C: KLL at 272 eV
- O: LMM at 120 eV

Ti: LMM at 418 eV In: MNN at 404 eV

Carbon contamination at the interface



Auger Depth Profiling





Auger Summary

- Very high spatial resolution (~ 10 nm) for Auger analysis, from the outer 2-3 nm of sample surface
- Much smaller analysis volume compared to SEM/EDX
- Elemental composition and some chemical state information
- Relatively high sensitivity for lower z elements
- Depth profiling, mapping, small spot analysis, and line scans



Thank You!



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